

### Features

- Ultra low capacitance: 0.35pF(IO to IO)
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Protects one power line and four data lines
- Flow-through package
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test  
Air discharge:  $\pm 25\text{kV}$   
Contact discharge:  $\pm 20\text{kV}$
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 5A (8/20  $\mu\text{s}$ )
- RoHS Compliant

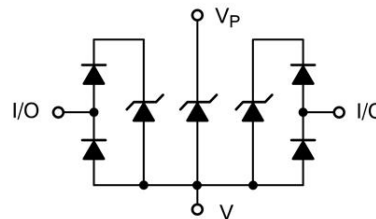
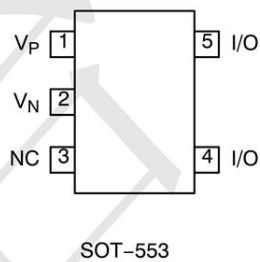
### Mechanical Characteristics

- Package: SOT-553
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Shipping Qty :4000pcs/7Inch Tape & Reel

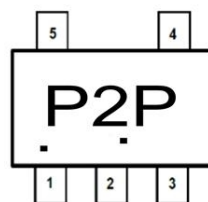
### Applications

- USB 2.0 and USB OTG
- Multi Media Card (MMC) Interfaces
- SD Card Interfaces
- MDDI Ports
- SIM Ports
- Key Pads

### Dimensions and Pin Configuration



### Marking



### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Current (8/20μs)	I <sub>PP</sub>	5	A
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±25	kV
ESD per IEC 61000-4-2 (Contact)		±20	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V <sub>RWM</sub>			5	V	Any I/O pin to ground
Breakdown Voltage	V <sub>BR</sub>	6			V	I <sub>T</sub> = 1mA, any I/O pin to ground
Reverse Leakage Current	I <sub>R</sub>			1	μA	V <sub>RWM</sub> = 5V, any I/O pin to ground
Clamping Voltage	V <sub>C</sub>			9	V	I <sub>PP</sub> = 1A (8 x 20μs pulse), any I/O pin to ground
Clamping Voltage	V <sub>C</sub>		11	16	V	I <sub>PP</sub> = 5 A (8 x 20μs pulse), any I/O pin to ground
Junction Capacitance	C <sub>J</sub>		0.7		pF	V <sub>R</sub> = 0V, f = 1MHz, any I/O pin to ground
Junction Capacitance	C <sub>J</sub>		0.35	0.6	pF	V <sub>R</sub> = 0V, f = 1MHz, between I/O pins

## Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise Specified)

Fig1. 8/20 $\mu\text{s}$  Pulse Waveform

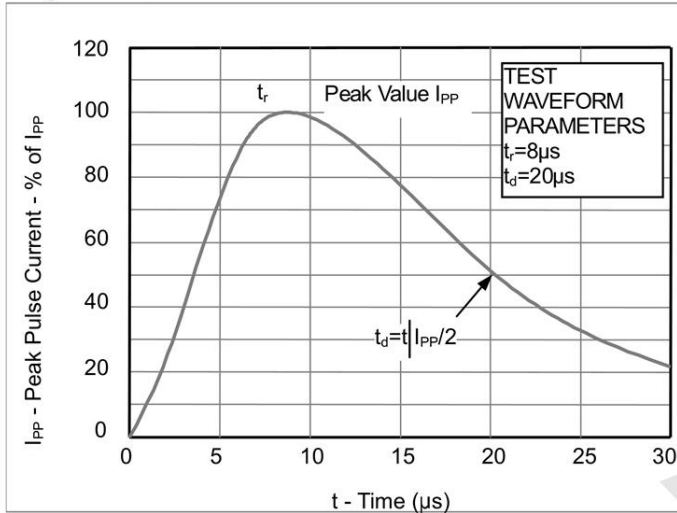


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

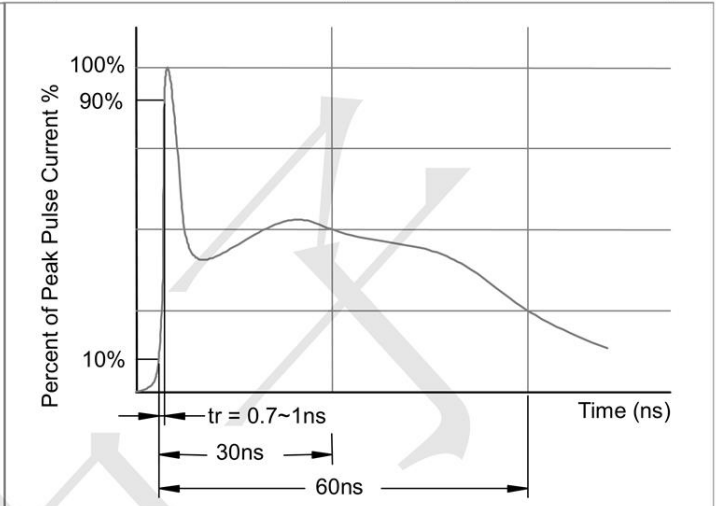
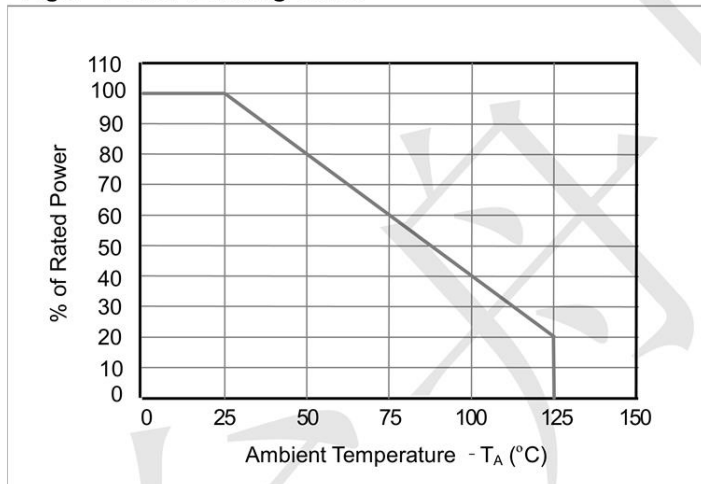
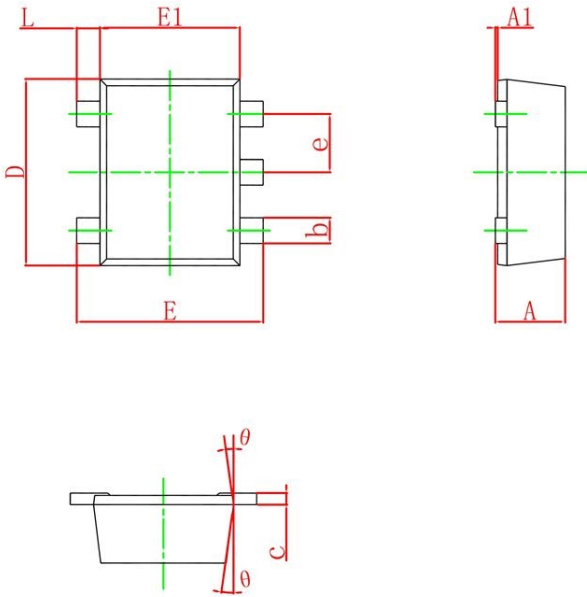


Fig3. Power Derating Curve





**SOT-553 -Package Outline Drawing**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.525	0.600	0.021	0.024
A1	0.000	0.050	0.000	0.002
e	0.450	0.550	0.018	0.022
c	0.090	0.160	0.004	0.006
D	1.500	1.700	0.059	0.067
b	0.170	0.270	0.007	0.011
E1	1.100	1.300	0.043	0.051
E	1.500	1.700	0.059	0.067
L	0.100	0.300	0.004	0.012
θ	7° REF.		7° REF.	

**Suggested Land Pattern**

